

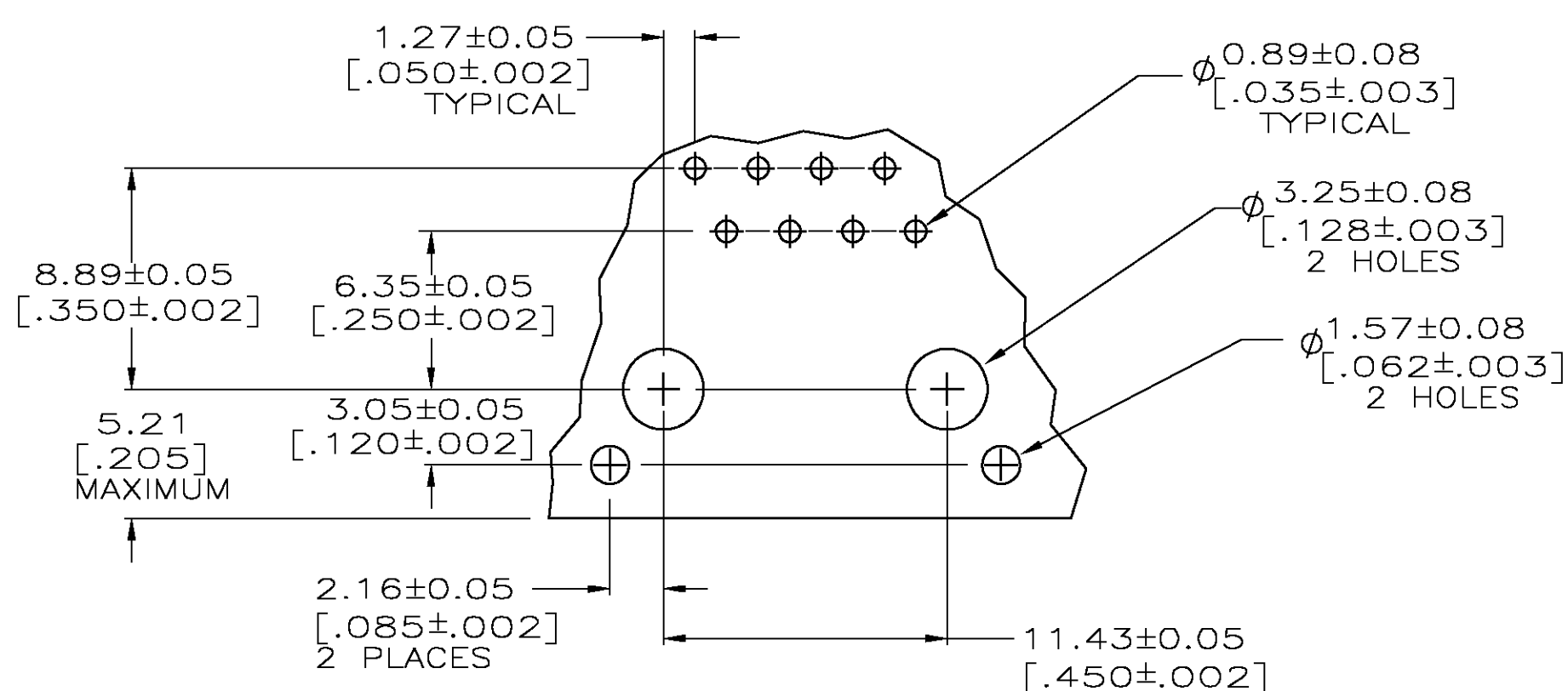
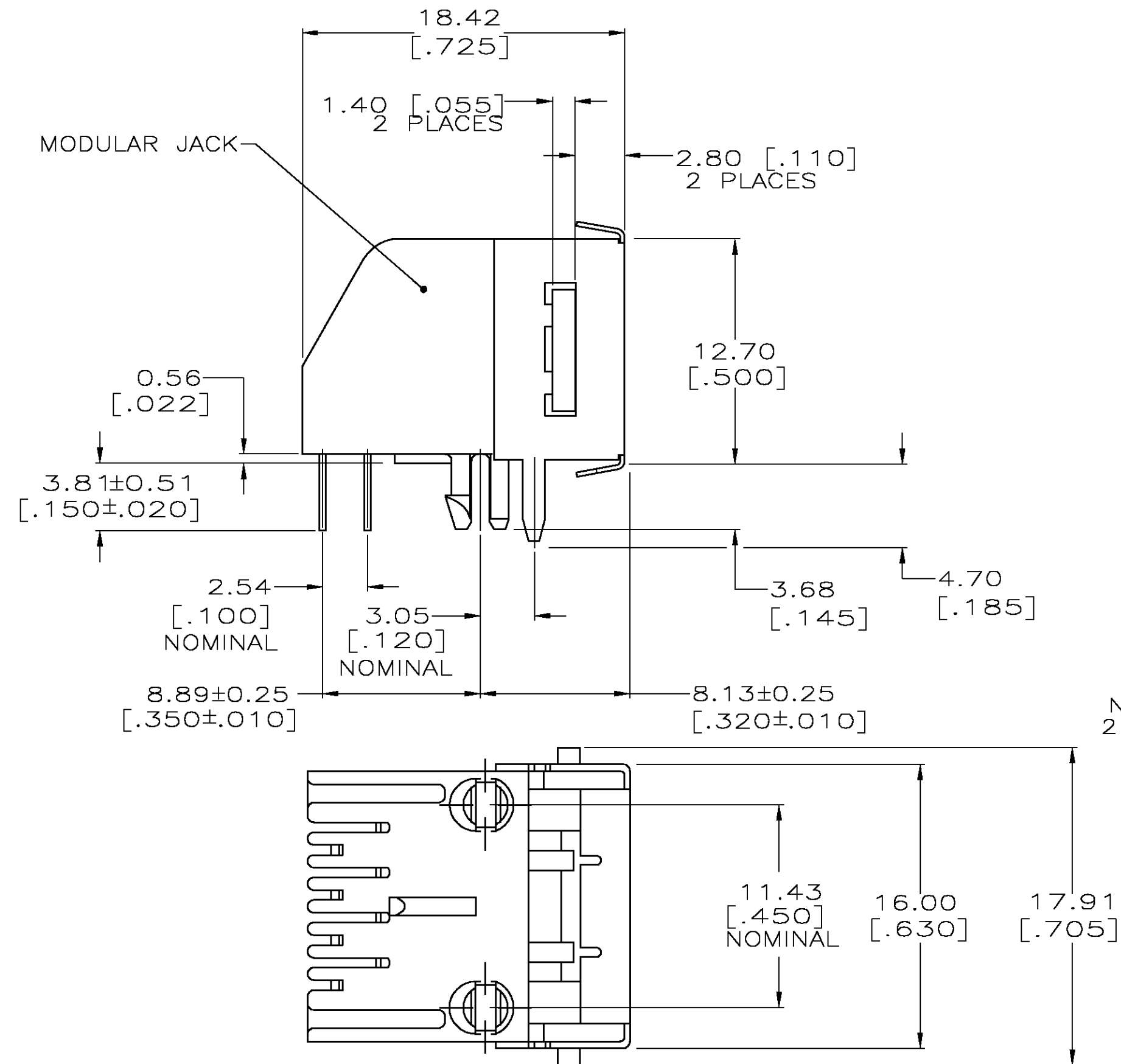
LOC	DIST	REVISIONS			
		P	LTR	DATE	DWN
AA	22	G		ADDED: -3 PER EC 0S11-0113-03	DD

D

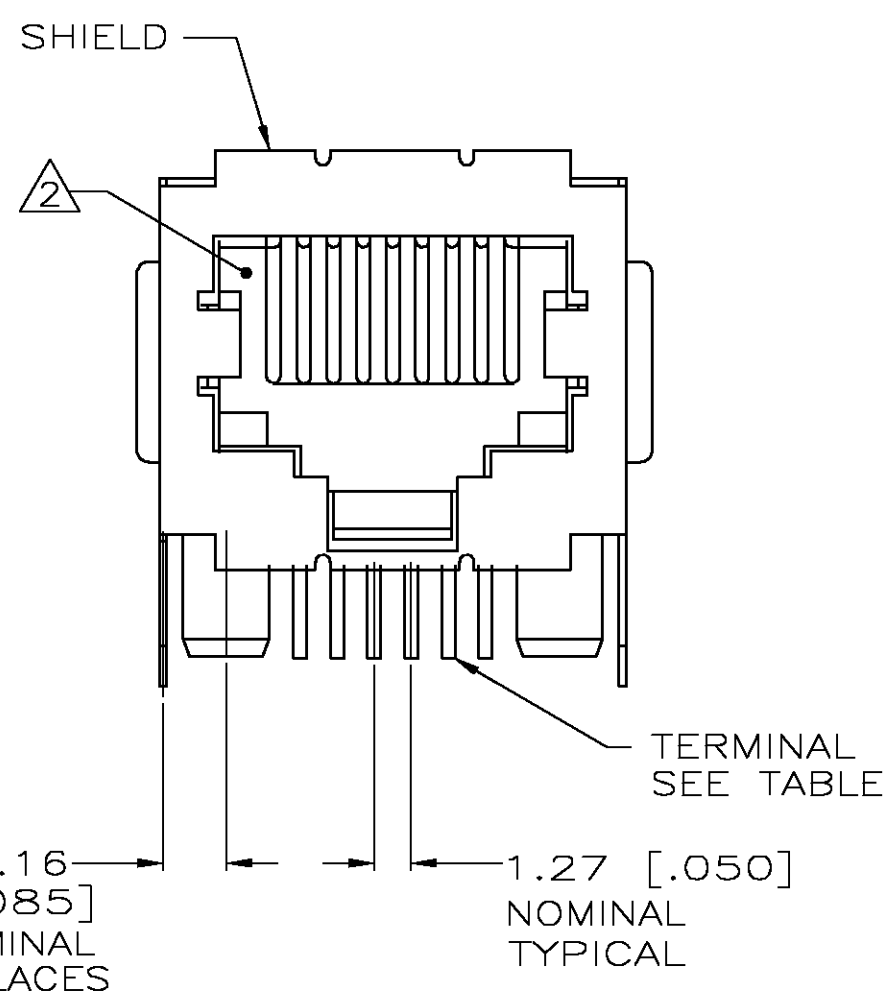
C

B

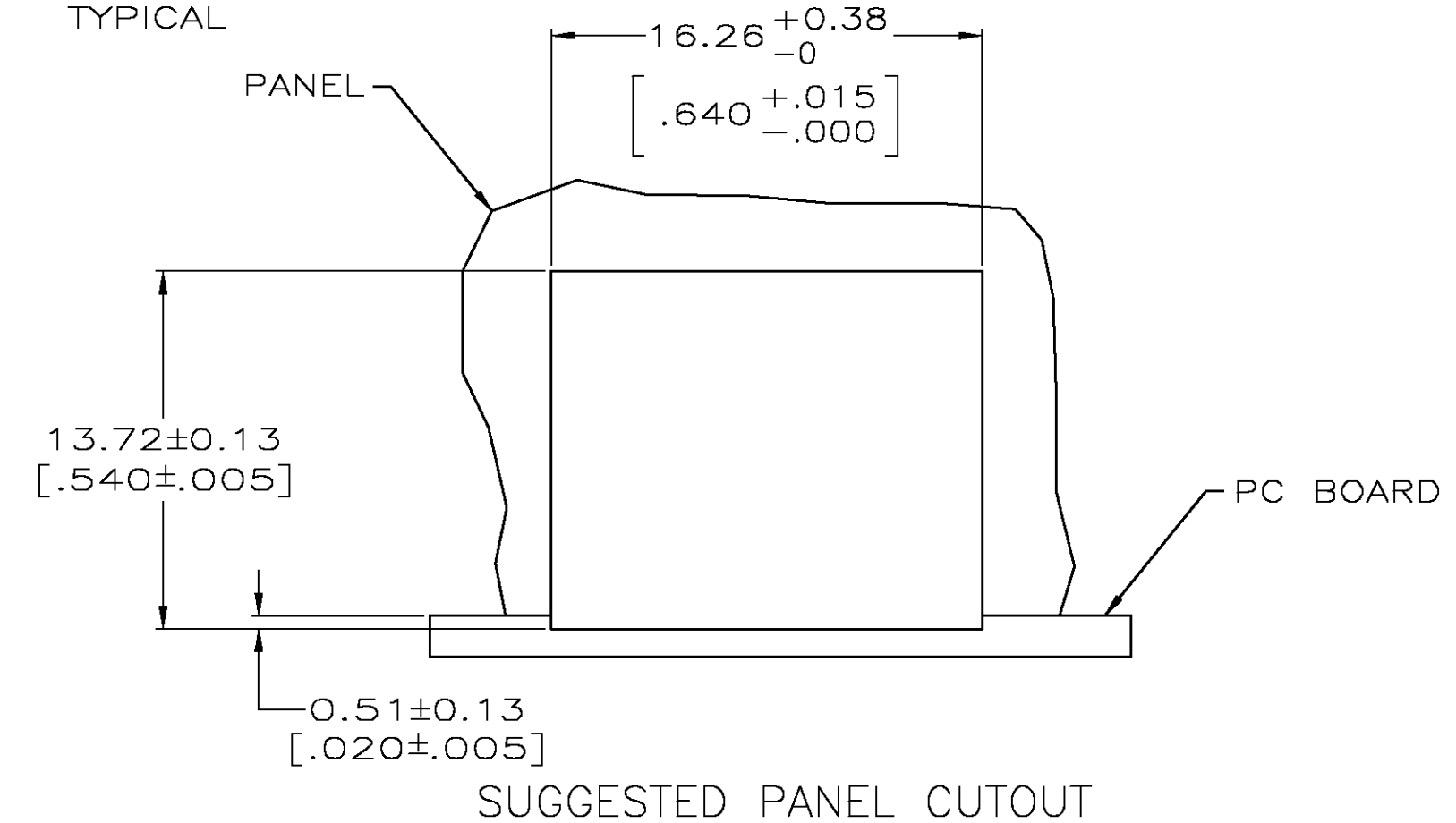
A



SUGGESTED PRINTED CIRCUIT BOARD MOUNTING HOLE LAYOUT VIEW SHOWN AS CIRCUIT SIDE OF BOARD



- 1 MATERIAL: HOUSING — PER TABLE, BLACK.
TERMINAL — 0.36 [.014] THICK PHOS-BRONZE PLATED WITH 1.27um [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81um [.000150] THICK TIN LEAD IN SOLDER AREA OVER 1.27um [.000050] THICK NICKEL UNDERPLATE
SHIELD — 0.25 [.010] THICK COPPER ALLOY, TIN-LEAD PLATED.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.



YES	HIGH TEMP NYLON	555141-3
NO	PBT POLYESTER	555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

DWN G. GARRETT	7-10-95	tyco Electronics	Tyco Electronics Corporation Harrisburg, PA 17105-3608
CHK N. JONES	8-25-95		
APVD J. TONEY	9-1-95	NAME	
PRODUCT SPEC 108-1163	MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS		
APPLICATION SPEC 114-2048	SIZE	CAGE CODE	DRAWING NO
WEIGHT —	A2	00779	C-555141
CUSTOMER DRAWING		SCALE	4:1
		SHEET	1 OF 1
		REV	C